



Product Change Notification: CENO-16EGCZ399

Date:

18-Sep-2025

Product Category:

16-Bit - Microcontrollers And Digital Signal Controllers, 16-Bit Microcontrollers, 32-Bit Microcontrollers, Development Tools, 8-Bit Microcontrollers, Access Networks, Analog Multiplexer/Switch ICs, Analog Temperature Sensors, Analog to Digital Converters, ARCNET-Circlink Controllers, Battery Management and Fuel Gauges - Battery Chargers, Battery Management and Fuel Gauges- Battery Management Devices (Powersmart), Bluetooth Silicon, Broadband Gateway, CAN Controller, CAN Controller With Integrated Transceiver, CAN PN Transceiver, CAN/LIN SBC, Capacitive Touch Sensors, Car Access, Charge Pump DC-To-DC Converters, Clock And Timing - Clock And Data Distribution, Clock And Timing - Clock Generation, Clock And Timing - High Speed Communication, Clock Buffers, Computing I/O Controllers, Crypto Authentication, Current And Power Measurement Ics, Digital Potentiometers, Digital Signal Controllers, Digital Temperature Sensors, Digital to Analog Converters, Driver / Interface ICs, Equalizers, Ethercat, Ethernet Bridges, Ethernet Controllers, Ethernet Phys, Ethernet Switches, General Purpose Fpgas, General Purpose LED Drivers, High Reliability, High-Side Current Sense Amplifiers, Hybrid Controllers, Inductive Position Sensors, INIC, Instrumentation Amplifier, Interface- Controller Area Network (CAN), Interface- Infrared Products, Interface- LCD Drivers, Interface- LIN Transceiver, Interface- Passive-Keyless-Entry Analog Front End, Interface- Serial Peripherals, KEELOQ® Encoder Devices, LIN System-In-Package, LIN Transceiver With Vreg, LIN Transceiver With Vreg And Watchdog Timer, Line Drivers, Linear Comparators, Linear Op Amps, Linear Programmable Gain Amplifiers, Linear Regulators, MCUs with transmitters, Memory, Motor Control Sips, Motor Drivers, Photoelectric/Ionization Smoke Detector, Piezoelectric Horn Drivers And CO Detector, PoE PSE, Power Line Communications, Power Management - PMIC, Power Management - Power Switches, Power Management - PWM Controllers, Power MOSFET Drivers, PWM Controllers, Random Number Generator, Real-Time Clock/Calendar, Security Computing Embedded Controllers, Simple and Complex Programmable Logic, Smart Energy SOC, Smart Energy Wireless Communications, Special Purpose Analog to Digital Converters, Switching Regulators, Temperature Sensors, Touch Controllers, Touchscreen Controllers, Transceivers, USB Bridge, USB Hubs, USB Port Power Controller, USB Power Delivery, USB Products, Voice Audio, Wireless IC, Wireless Modules, Wireless Power And USB-PD Controller

Notification Subject:

CCBs 7684, 7686, 7703, 7704, 6429.001 and 7042.001 Final Notice: Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

Affected CPNs:

CENO-16EGCZ399_Affected_CPN_09182025.pdf
CENO-16EGCZ399_Affected_CPN_09182025.csv

Notification Text:

PCN Status:

Final Notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:

Qualification of QMI519 as a new die attach material and CuPdAu as a new bond wire material for various products available in PLCC, QSOP, SOIC, SOIJ, SSOP, TSSOP, MQFP, TQFP, DFN, QFN, QFN-S, SQFN, TDFN, UDFN, UQFN, VDFN, VQFN, WQFN and TQFP packages assembled at MP3A, MTAI and MMT sites.

Pre and Post Change Summary:

For PIC16F182xx, PIC16F151xx, PIC16F193xx, PIC16F726xx, PIC16F178xx, PIC18F24Kxx, PIC16F722xx, PIC16F723xx, PIC18F23Kxx, PIC16LF19xx, PIC16LF15xx, PIC16F171xx, PIC16F188xx, PIC16F191xx, PIC16F153xx, PIC18F26Kxx, PIC18F25Kxx, PIC16F184xx, PIC16F150xx, PIC16F145xx, PIC16F161xx, PIC16F157xx, PIC16F170xx, PIC16F183xx and MTCH108 device families available in 16L, 20L and 28L UQFN (3x3x0.5mm, 4x4x0.55mm and 4x4x0.5mm) packages

	Pre Change	Post Change
Assembly Site	Microchip Technology Thailand (Branch) (MMT)	Microchip Technology Thailand (Branch) (MMT)
Wire Material	Au	CuPdAu
Die Attach Material	8600	QMI519*
Molding Compound Material	G700	G700
Lead-Frame Material	EFTEC64T	EFTEC64T

For ATmega328PB, ATmega88PB, ATmega48PB, ATMEGA4808 and ATmega168PB device families available in 32L TQFP (7x7x1mm) package.

	Pre Change	Post Change
Assembly Site	Microchip Technology Thailand (HQ) (MTAI)	Microchip Technology Thailand (HQ) (MTAI)
Wire Material	Au	CuPdAu
Die Attach Material	3280	QMI519*
Molding Compound Material	G700	G700
Lead-Frame Material	C7025	C7025

For remaining device families and packages.

	Pre Change			Post Change		
Assembly Site	Microchip Technology Thailand (HQ) (MTAI)	Microchip Technology Thailand (Branch) (MMT)	Microchip Technology Inc. (MPHIL-3) (MP3A)	Microchip Technology Thailand (HQ) (MTAI)	Microchip Technology Thailand (Branch) (MMT)	Microchip Technology Inc. (MPHIL-3) (MP3A)
Wire Material	Au / CuPdAu			Au / CuPdAu		
Die Attach Material	3280 / 8600 / 2200D			QMI519*		
Molding Compound Material	G600 / G700			G600 / G700		
Lead-Frame Material	A194 / C151 / CDA151/ EFTEC64T / C7025			A194 / C151 / CDA151/ EFTEC64T / C7025		

Note 1: **PFAS free material*

Impacts to Data Sheet:

None

Change Impact

None

Reason for Change:

To improve manufacturability by qualifying QMI519 as a new die attach to standardize the use of PFAS free material and CuPdAu as a new bond wire material.

Change Implementation Status:

In Progress

Estimated First Ship Date:

September 03, 2025 (date code: 2536)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	July 2025					>	September 2025				
Workweek	27	28	29	30	31		36	37	38	39	40
Qual Report Availability				x							
Final PCN Issue Date				x							
Estimated Implementation Date							x				

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qualification Report List

Revision History:

July 22, 2025: Issued final notification.

August 15, 2025: Re-issued the final notification to update the qualification report list, which now includes either a link to the qual report or an attached PDF file for each CCB. Updated the affected CPN list to removed EOL'ed CPNS: ATECC608A-MAHLG-T, ATECC608A-MAHVL-T, ATECC608A-MAHVM-T, ATECC508A-MAHPH-S, ATECC508A-MAHUW-T, ATECC608B-MAH5O-T, ATECC508A-MAHKN-T, ATECC608B-MAHAF-S, ATECC508A-MAHKN-S, ATECC508A-MAH1A-T, ATECC608A-MAH4K-T, ATECC608A-MAH3P-T, ATECC608A-MAH3Q-S, ATECC608A-MAH4W-T, ATECC608A-MAHAC-S, ATECC608A-MAHD3-S, ATECC608A-MAHGA-T, ATECC608A-MAHGX-T, ATECC508A-MAH2E-T, ATECC608A-MAH2B-T, ATECC608A-MAH2G-S, ATECC608A-MAHT2-B, ATECC508A-MAH1C-S, ATECC508A-MAH1Q-S, ATECC508A-MAH1Q-T, ATECC608A-MAH1G-S, ATECC608A-MAH1G-T, ATECC608A-MAH1K-S, ATECC508A-MAHWW-S, ATECC508A-MAHWW-T, ATECC608B-MAHAK-S, ATECC608B-MAHPA-T, ATECC608B-MAHSB-T, ATECC608B-MAHSC-T, ATECC608A-MAH2U-T, ATECC608A-MAH2V-S, ATECC608A-MAH2X-S,

ATECC608A-MAH2Y-S, ATECC608A-MAH3J-T and ATECC608A-MAH1W-T.

September 18, 2025: Re-issued the final notification to add PFAS Elimination and Die Attach Explanation file and updated the affected CPN list to remove ATMEGA8535L-8JU, AT89LP6440-20JU, X34070T-H/ST, LX34050QPW-TR, LX3302AQPW-TR-EASY, LX3302AQPW-TR-C01, LX34311T-H/ST, LX34070AT-H/ST, LX34070-H/ST, LX34050QPW, LX3302AQPW-EASY, LX34070T-H/STVAO, LX3302AQPW-TR, LX34050QPW-TR-VAO, LX3302AQPW-TR-GM, LX34311T-H/STVAO, LX34070AT-H/STVAO, LX34070-H/STVAO, LX3302AQPW and LX34050QPW-VAO.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PFAS Elimination and Die Attach_Explanation.pdf](#)
[PCN_CENO-16EGCZ399 - Qualification-Report-List.xlsx](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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